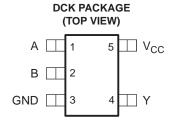
SCES679-JULY 2007

#### **FEATURES**

- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Supports 5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 6.7 ns at 3.3 V
- Low Power Consumption, 15-μA Max I<sub>CC</sub>
- ±24-mA Output Drive at 3.3 V
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over specified temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

# **DESCRIPTION/ORDERING INFORMATION**

This single 2-input exclusive-OR gate is designed for 1.65-V to 5.5-V V<sub>CC</sub> operation.

The SN74LVC1G86 performs the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If the input is low, the other input is reproduced in true form at the output. If the input is high, the signal on the other input is reproduced inverted at the output.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAG	iE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>	
-55°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74LVC1G86MDCKREP	CJ_	

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(3) DCK: The actual top-side marking has one additional character that designates the assembly/test site.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

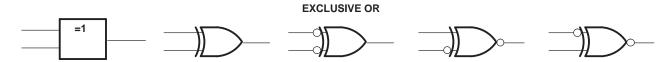


#### **FUNCTION TABLE**

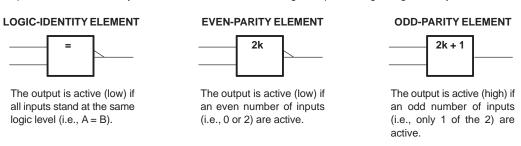
INPL	INPUTS						
Α	A B						
L	L	L					
L	Н	Н					
Н	L	Н					
Н	Н	L					

## **EXCLUSIVE-OR LOGIC**

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an SN74LVC1G86 gate in positive logic; negation may be shown at any two ports.





# SN74LVC1G86-EP SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCES679-JULY 2007

# Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	6.5	V	
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state (2)			6.5	V
Vo	Voltage range applied to any output in the high or low state (2)(3)				V
$I_{IK}$	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND				mA
$\theta_{JA}$	Package thermal impedance (4)		252	°C/W	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The value of  $V_{CC}$  is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVC1G86-EP SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCES679-JULY 2007



# Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT
V	Cumply yeltogo	Operating	1.65	5.5	V
$V_{CC}$	Supply voltage	Data retention only	1.5		V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 X V <sub>CC</sub>		
V	Lligh level input veltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V
$V_{IH}$	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 X V <sub>CC</sub>		
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 X V <sub>CC</sub>	
\/	Low level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		0.8	V
		V <sub>CC</sub> = 4.5 V to 5.5 V		0.3 X V <sub>CC</sub>	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
	High-level output current	V <sub>CC</sub> = 2.3 V		-8	
$I_{OH}$		V 0.V		-16	mA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 4.5 V		-32	
		V <sub>CC</sub> = 1.65 V		4	
		V <sub>CC</sub> = 2.3 V		8	
$I_{OL}$	Low-level output current	V 0.V		16	mA
		V <sub>CC</sub> = 3 V		24	
		V <sub>CC</sub> = 4.5 V		32	
		$V_{CC}$ = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1		ns/V
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5	
T <sub>A</sub>	Operating free-air temperature	•	-55	125	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS	V		T <sub>A</sub> = 25°C	−55°C to 125°C	LINUT
PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup> MAX	MIN MAX	UNIT
	I <sub>OH</sub> = -100 μA	1.65 V to 5.5 V	V <sub>CC</sub> - 0.1		V <sub>CC</sub> - 0.1	
	I <sub>OH</sub> = -4 mA	1.65 V	1.2		1.2	
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		1.9	V
V <sub>OH</sub>	$I_{OH} = -16 \text{ mA}$	3 V	2.4		2.4	v
	$I_{OH} = -24 \text{ mA}$	3 V	2.3		2.3	
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8		3.8	
	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V		0.1	0.1	
	I <sub>OL</sub> = 4 mA	1.65 V		0.45	0.45	
V <sub>OL</sub>	$I_{OL} = 8 \text{ mA}$	2.3 V		0.3	0.3	V
V OL	I <sub>OL</sub> = 16 mA	3 V		0.4	0.4	v
	I <sub>OL</sub> = 24 mA	3 V		0.55	0.55	
	I <sub>OL</sub> = 32 mA	4.5 V		0.55	0.55	
I <sub>I</sub> A or B input	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V		±5	±5	μA
I <sub>off</sub>	$V_I$ or $V_O = 5.5 \text{ V}$	0		±10	±10	μA
Icc	$V_1 = V_{CC} \text{ or } $ $I_O = 0$	1.65 V to 5.5 V		10	15	μA
Δl <sub>CC</sub>		3 V to 5.5 V		500	500	μА
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V		6		pF

<sup>(1)</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.

# **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 ± 0.3 V		۷ <sub>CC</sub> = ± 0.		UNIT
	(INPUT)	(001701)	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	1.3	6.7	1	5.7	ns

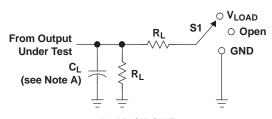
# **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> = 5 V	UNIT
	PARAMETER	TEST CONDITIONS	TYP	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	22	24	pF



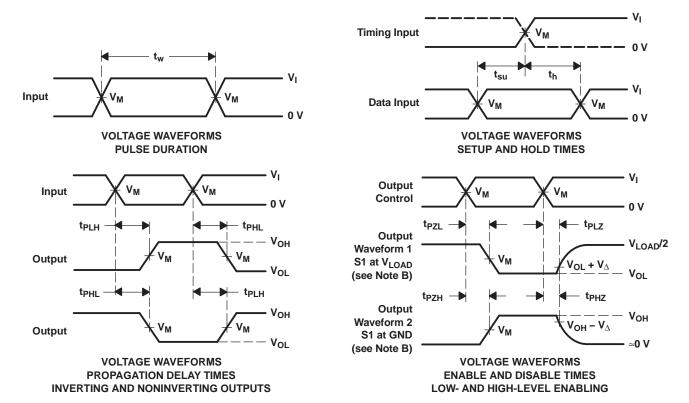
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

V	INF	PUTS	· ·	V	•		V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\!\scriptscriptstyle \Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	<b>1 M</b> Ω	0.3 V
5 V ± 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.3 V



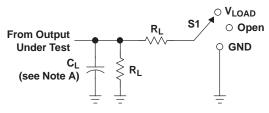
NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



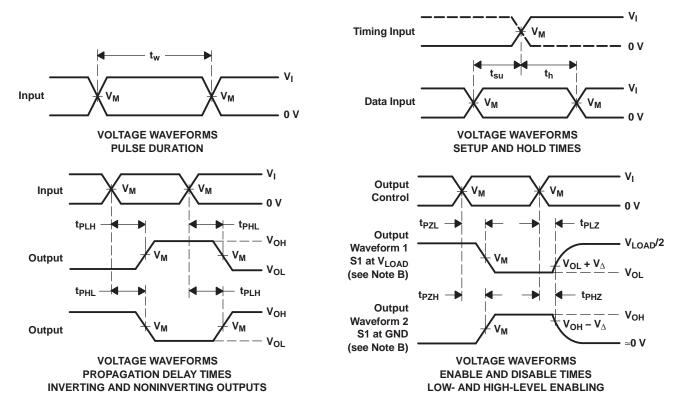
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

V	INF	PUTS	· ·	V	•		V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V $\pm$ 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50 pF	500 Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



# PACKAGE OPTION ADDENDUM

6-Feb-2020

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC1G86MDCKREP	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CJY	Samples
V62/06666-01XE	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CJY	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

6-Feb-2020

#### OTHER QUALIFIED VERSIONS OF SN74LVC1G86-EP:

• Automotive: SN74LVC1G86-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

# PACKAGE MATERIALS INFORMATION

www.ti.com 3-Aug-2017

# TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	N	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G86MDCKREP	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3

www.ti.com 3-Aug-2017



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G86MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0

# DCK (R-PDSO-G5)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



# DCK (R-PDSO-G5)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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